

ICP Test Report Certification Packet

Company name:	Littelfuse, Inc.
Product Series:	Class J (100 A) & HR (250V 100A) Series
Product #:	LFJ 100A, LFJ601003CID, HR (250V 100A)
Issue Date:	January 25, 2012

It is hereby certified by Littelfuse, Inc. that there is neither RoHS (EU Directive 2002/95/EC)-restricted substance nor such use, for materials to be used for unit parts, for packing/packaging materials, and for additives and the like in the manufacturing processes. In addition, it is hereby reported to you that the parts and sub-materials, the materials to be used for unit parts, the packing/packaging materials, and the additives and the like in the manufacturing processes, are all composed of the following components.

Issued by: KRISTEEN

<Global EHS Engineer>

(1) Parts, sub-materials and unit parts This document covers the J 100 A and HR 250V 100A RoHS-Compliant series products manufactured by Littelfuse, Inc.

< Raw Materials Used Please see Table 1

(2) The ICP data on all measurable substances

Please see appropriate pages as identifed in Table 1

Remarks :



Total Parts	Raw Material Part Number	Raw Material Description	Page(s)
1	NA	Base – BMC FTI400	3-9
2	NA	Indicator – PC2407	10-15
6	NA	Terminal Block - Aluminum	16-20
7	NA	Set screws - Aluminum	16-20
	NA	Screws, Nuts & Bolts - Zinc Plated	
8		Steel	21-25
9	NA	Clip - T3 Copper Alloy	26-30
		Spring Clamp/ Reinforcing Clip -	
10	NA	65Mn	31-35
12	NA	Neon Lamp Sub-assay	35-46
13	NA	Tin Plating	47-50
14	NA	Zinc Plating	51-54
15	NA	Ероху	55-62

Table 1: List of Raw Materials covered by this report



TEST REPORT

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APPLICANT	: BMC CHINA CO., LIMITED A AREA11-12 XISHAN ECONOMIC DEVELOPMENT ZONE PRIVATELY OWNED SCIENCE AND TECHNOLOGY INDUSTRIAL PARK WUXI JIANGSU PROVINCE CHINA
申请人公司名称	: 无锡荣迈工程塑料有限公司 江苏省无锡市锡山经济开发区私营科技工业园 A 区 11-12
DATE OF SUBMISSION	: July 21, 2011
样品收取日期	: 2011年7月21日
TEST PERIOD	: July 21, 2011 to July 27, 2011
所需工作周期	: 2011 年 7 月 21 日 至 2011 年 7 月 27 日
NO. OF WORKING DAY(S)	: 5
所需工作日	: 5
SAMPLE DESCRIPTION 样品描述	: One (1) received sample stated to be 团状模塑料(gray plastic) Style No.: FTI400(灰色)
TESTED ITEM 1 测试项目 1	: Gray plastic

SUMMARY OF TEST RESULTS 测试结果摘要

TEST REQUESTED	PASS	FAIL
测试项目	通过	不通过
Restriction of Hazardous Substances Directive (RoHS), 2002/95/EC 有关欧洲针对电子产品的指令(电子电器禁用某些有害物质指令), 2002/95/EC	1	

REMARK

If there are questions or concerns on this report, please contact the following persons: 若有任何疑问或咨询,可通过下述联络方式与我们联络 General enquiry and invoicing 其他问题 (021) 24166888*6837/6842 Technical enquiry 技术问题 (021) 24166888*6860/6856

顾晶/许祥晖 小姐 Ms. Michelle Gu/Lucy Xu Michelle.gu@cn.bureauveritas.com/ Lucy.xu @cn.bureauveritas.com 余克刚/郭晔轩 先生 Mr. Gorden.Yu/ Kevin Guo

Gorden.Yu@cn.bureauveritas.com/ Kevin.guo@cn.bureauveritas.com

BUREAU VERITAS CONSUMER PRODUCTS SERVICES DIVISION (SHANGHAI) 必维国际检验集团 --必维申美商品检测(上海)有限公司

PREPARED BY : 制定:

RW/2011

Bureau Veritas Consumer Products Services Division (Shanghai) No. 168, Guanghua Road, Zhuangiao Town, Minhang, Shanghai, China. Post Code: 201108 Tel: 86-21-24081888 Fax: 86-21-64890042 Email: bvcps sh. info@cn.bureauveritas.com Http:www.bureauveritas.com/cps

Zero

郭晔轩 Kevin Guo 电子电器分析部实验室经理 Electrical & Electronic Analytical LABORATORY MANAGER

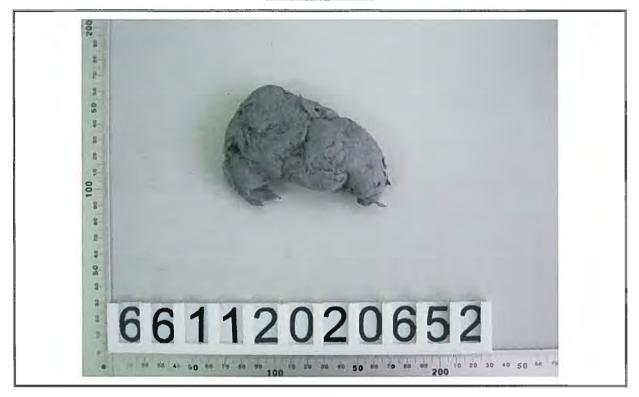
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Photo of the Submitted Sample 递交样品照片





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TEST RESULT 测试结果

<u>Restriction of Hazardous Substances Directive (RoHS), 2002/95/EC</u> 有关欧洲针对电子产品的指令(电子电器禁用某些有害物质指令), 2002/95/EC

Compounds 化合物	Tested item 测试项目 (mg/kg)	RoHS' Limits RoHS' 建议最高界限
	1	(mg/kg)
Lead 铅 (Pb)	183	1000
Mercury 汞 (Hg)	ND	1000
Cadmium 镉 (Cd)	ND	100
Chromium VI 六价铬 (Cr VI)	ND	1000
Polybrominated Biphenyls 多溴联苯 (PBBs):	
Bromobiphenyls 一溴联苯	ND	N
Dibromobiphenyls 二溴联苯	ND	\neg
Tribromobiphenyls 三溴联苯	ND	\neg
Tetrabromobiphenyls 四溴联苯	ND	
Pentabromobiphenyls 五溴联苯	ND	\neg
Hexabromobiphenyls 六溴联苯	ND	\neg \land
Heptabromobiphenyls 七溴联苯	ND	
Octabromobiphenyls 八溴联苯	ND	
Nonabromobiphenyls 九溴联苯	ND	
Decabromobiphenyl十溴联苯	ND	
Sum of PBBs 多溴联苯总和	ND	1000
Polybrominated Diphenyl Ethers 多溴联苯	谜 (PBDEs):	
Bromodiphenyl ethers 一溴联苯醚	ND	N
Dibromodiphenyl ethers 二溴联苯醚	ND	\neg
Tribromodiphenyl ethers 三溴联苯醚	ND	
Tetrabromodiphenyl ethers 四溴联苯醚	ND	\neg \setminus
Pentabromodiphenyl ethers 五溴联苯醚	ND	
Hexabromodiphenyl ethers 六溴联苯醚	ND	\neg \land
Heptabromodiphenyl ethers 七溴联苯醚	ND	
Octabromodiphenyl ethers 八溴联苯醚	ND	
Nonabromodiphenyl ethers 九溴联苯醚	ND	
Decabromodiphenyl ether 十溴联苯醚	ND	
Sum of PBDEs 多溴联苯醚总和	ND	1000

Tested Item 测试项目	Conclusion 结论
1) Gray plastic	PASS 通过



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Note / 注释:

Regulated Substances 受限物	贡 Detection limit 检测限	RoHS' Limit (mg/kg) RoHS'建议最高界限
Pb 铅	2	1000
Hg汞	2	1000
Cd 镉	2	100
Cr VI 六价铬	2	1000
PBBs 多溴联苯	5 (each)	1000 (sum)
Bromobiphenyls		
Dibromobiphenyls		
Tribromobiphenyls		
Tetrabromobiphenyls		
Pentabromobiphenyls		
Hexabromobiphenyls		
Heptabromobiphenyls		
Octabromobiphenyls		
Nonabromobiphenyls		
Decabromobiphenyl		
PBDEs 多溴联苯醚	5 (each)	1000 (sum)
Bromodiphenyl ethers		
Dibromodiphenyl ethers		
Tribromodiphenyl ethers		
Tetrabromodiphenyl ethers		
Pentabromodiphenyl ethers		
Hexabromodiphenyl ethers		
Heptabromodiphenyl ethers		
Octabromodiphenyl ethers		
Nonabromodiphenyl ethers		
Decabromodiphenyl ether		
mg/kg= ppm 百万分之 <	= less than 少于 ND =	not detected 不被检出 NA = not applicable

Ph = I ead 铅 Hg = Mercury 汞

Br = Bromine 溴

Test Method / 测试方法:

Wet Chemistry Tests -- Reference to IEC 62321:2008, "Electrotechnical Products- Determination of Levels of Six Regulated Substances": 湿化学 方法 - 参照 IEC 62321:2008, 电子电器产品中六种限用物质浓度测定

Cd = Cadmium 磁

Cr = Chromium 铬

PBDEs = Polybrominated Diphenyl Ethers 多溴联苯醚

Lead (Pb) and Cadmium (Cd): The sample is comminuted and digested with acid mixtures. Pb/ Cd contents are determined with ICP-AES i. technique. (Chapter 8, 9 & 10)

铅和镉: 先将样品粉碎, 然后用混酸消解。铅/镉的含量由等离子发射光谱仪测定(第8,9和10章)。

PBBs = Polybrominated Biphenyls 多溴联苯

ii. Mercury (Hg): The sample is comminuted and digested with acid mixtures. Hg content is determined with ICP-AES, ICP-MS or AAS-VGA technique. (Chapter 7)

汞: 先将样品粉碎, 然后用混酸消解。汞含量由离子发射光谱仪, 或者原子吸收分光光度计-氢化物发生装置测定。(第7章) iii. Chromium (VI) (Cr VI) 六价铬:

Metal: Qualitative method for the presence of hexavalent chromium on metal surface on "Test for the presence of Hexavalent Chromium (Cr (VI)) in colourless and coloured corrosion-protection coatings on metals". The presence of hexavalent chromium is indicated by the formation of a red to violet color. The method is applied in turn to 1) untreated surface: 2) surface got by gently rubbing to scratch possibly reduced chromate surface but without completely removing the whole coating layer; 3) surface got by forcibly scratching into the deeper layers, even reaching the substrate. The sample is further verified by boiling water extraction method if the result of spot test shows ahead is negative or uncertain. (Annex B)

金属: 金属表面六价铬存在的定性方法"金属表面无色和有色腐蚀防护涂层中六价铬(Cr VI)的测试"测试颜色呈红一紫 色,则表明六价铬的存在。该方法适用于 1)未磨损过的表面;2)轻微磨损过的表面,以去除可能被还原的铬酸盐表层,但 不去除整个镀层;3)用力磨损的镀层表面,甚至于基材表面。如果以上点测试结果量阴性或无法确定,则用沸水萃取方法作进 步确认 (附录 B)

Plastics & Electronics : The sample is comminuted and digested with alkaline mixtures. Chromium VI content is determined with UV-B. VIS spectroscopic technique. (Annex C)

IV. PBBs and PBDEs: The sample extracted by appropriate solvent is used for extraction and quantified GC-MS. (Annex A) 多溴联苯和多溴联苯醚:将样品用合适溶液进行提取,再由气相色谱-质谱联用仪测定。(附录 A)

Remark / 备注:

- For Chromium VI of a metal composite sample by wet chemistry, each individual metal component was tested. 1.
- 湿化学方法测试复合金属样品中六价铬时,每一个金属部分均被测试。 Negative means hexavalent chromium on the tested areas does not be detected at the time of testing. 2.
- 阴性结果表示测试时测试表面六价铬未被检出。
- Positive means the presence of hexavalent chromium on the tested area. If the test result is positive, that means the Cr(VI) concentration detected in the spot-test solution is equal to or greater than 1 mg/kg or if use boiling-water extraction, the concentration is equal to or greater than 0.02mg/kg/50cm². However, it shall not be interpreted as the Cr(VI) concentration in the coating layer of the sample and should not be used as a method detection limit for this qualitative test.

阳性结果表示测试表面存在六价铬。如果测试结果呈阳性,说明在点测试溶液中六价铬的浓度等于或大于 1mg/kg,或用水 煮法时六价 铬的浓度等于或大于 0.02mg/kg/50cm²。但这不应当作为样品镀层中六价铬的浓度,也不应当用作方法检出限,这只是一种定性的测试方 法。

塑料和电子器件:先将样品粉碎,然后用混碱消解,六价铬含量由紫外可见分光光度计测定。(附录 C)



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4. The results of lead, Cadmium, Mercury, PBB and PBDE of the tested item(s) meet the requirement of the EU directive 2002/95/EC(RoHS); and for the metallic sample with corrosion protection coating, the exact hexavalent chromium concentration of the surface coating cannot be determined by this qualitative test method (see remark 2 ahead) directly; so whether the tested item(s) meet(s) the EU directive RoHS or not, further confirmation and analysis should be done.

检测项目中铅,锅,汞,多溴联苯和多溴联苯醚的含量符合欧盟 RoHS 限量要求.对有腐蚀防护镀层的金属样品,镀层表面的六价铬准确含量则 无通过此定性方法确定;若需确定是否符合欧盟 RoHS,需要进一步确认和分析。

5. The result relates only to the tested item. The report shall not be reproduced except full without the written approval of the testing laboratory. Parameters which are not covered by the lab's testing scope are subcontracted to laboratories with government approval. The accreditation relates to competences given in the accreditation certificate. 测试结果仅代表被测样品。未经实验室书面许可,此报告不可被复制。对于本实验室未能涵盖的测试项目,实验室可以分包给其它政府承认的实验室。分包实验室的能力验证会在验证证书中注明。

<u>END</u>



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ANNEX-List of Exempted Specific Applications	in RoHS Directive (2010/571/EU).

1 1(a)	Exemption	
l(a)		Scope and dates of applicability
	Mercury in single capped (compact) fluorescent lamps not exceeding (per burner);	
	For general lighting purposes < 30 W: 5 mg	Expires on 31 December 2011; 3,5 mg may be used per burner after 31 December 2011 until 31
		December 2012; 2,5 mg shall be used per burner after 31 December 2012
1(b)	For general lighting purposes ≥ 30 W and ≤ 50 W 5 mg	Expires on 31 December 2011; 3,5 mg may be used per burner after 31 December 2011
1(c)		Expres on 51 December 2011, 5,5 mg may be used per burner after 51 December 2011
	For general lighting purposes ≥ 50 W and < 150 W 5 mg	
1(d)	For general lighting purposes ≥ 150 W: 15 mg	
1(e)	For general lighting purposes with circular or square structural shape and tube diameter < 17 mm	No limitation of use until 31 December 2011; 7 mg may be used per burner after 31 December 2011
l(f)	For special purposes: 5 mg	
2(a)	Mercury in double-capped linear fluorescent lamps for general lighting purposes not exceeding (per lamp):	
2(a)(1)	Tri-band phosphor with normal lifetime and a tube diameter < 9 mm (e.g. T2): 5 mg	Expires on 31 December 2011; 4 mg may be used per lamp after 31 December 2011
2(a)(2)	Tri-band phosphor with normal lifetime and a tube diameter ≥ 9 mm and ≤ 17 mm (e.g. T5), 5 mg	Expires on 31 December 2011; 3 mg may be used per lamp after 31 December 2011
2(a)(3)	Tri-band phosphor with normal lifetime and a tube diameter > 17 mm and \leq 28 mm (e.g. T8) 5 mg	Expires on 31 December 2011; 3,5 mg may be used per lamp after 31 December 2011
2(a)(4)	Tri-band phosphor with normal lifetime and a tube diameter > 28 mm (e.g. T12); 5 mg	Expires on 31 December 2012; 3,5 mg may be used per lamp after 31 December 2012
2(a)(5)	Tri-band phosphor with long lifetime (> 25 000 h) 8 mg	Expires on 31 December 2011; 5 mg may be used per lamp after 31 December 2011
2(b)	Mercury in other fluorescent lamps not exceeding (per lamp):	Expires on 51 December 2011, 5 mg may be used per tamp anet 51 December 2011
2(b)(1)	Linear halophosphate lamps with tube > 28 mm (e.g. T10 and T12): 10 mg	Expires on 13 April 2012
2(b)(2)	Non-linear halophosphate lamps (all diameters): 15 mg	Expires on 13 April 2016
2(b)(3)	Non-linear tri-band phosphor lamps with tube diameter $> 17 \text{ mm}$ (e.g. T9)	No limitation of use until 31 December 2011; 15 mg may be used per lamp after 31 December 2011
2(b)(4)	Lamps for other general lighting and special purposes (e.g. induction lamps)	No limitation of use until 31 December 2011; 15 mg may be used per lamp after 31 December 2011
3	Mercury in cold cathode fluorescent lamps and external electrode fluorescent lamps (CCFL and EEFL) for special pu	
3(a)		
	Short length (≤ 500 mm)	No limitation of use until 31 December 2011; 3,5 mg may be used per lamp after 31 December 2011
3(b)	Medium length (> 500 mm and \leq 1 500 mm)	No limitation of use until 31 December 2011; 5 mg may be used per lamp after 31 December 2011
3(c)	Long length (> 1 500 mm)	No limitation of use until 31 December 2011; 13 mg may be used per lamp after 31 December 2011
4(a)	Mercury in other low pressure discharge lamps (per lamp)	No limitation of use until 31 December 2011; 15 mg may be used per lamp after 31 December 2011
4(b)	Mercury in High Pressure Sodium (vapour) lamps for general lighting purposes not exceeding (per burner) in lamps	
4(b)-l	$P \le 155 \text{ W}$	No limitation of use until 31 December 2011; 30 mg may be used per burner after 31 December 2011
4(b)-11	155 W < P ≤ 405 W	
		No limitation of use until 31 December 2011: 40 mg may be used per burner after 31 December 2011
4(b)-III	P > 405 W	No limitation of use until 31 December 2011; 40 mg may be used per burner after 31 December 2011
4(c)	Mercury in other High Pressure Sodium (vapour) lamps for general lighting purposes not exceeding (per burner):	
4(c)-l	P ≤ 155 W	No limitation of use until 31 December 2011; 25 mg may be used per burner after 31 December 2011
4(c)-11	$155 \text{ W} \le P \le 405 \text{ W}$	No limitation of use until 31 December 2011; 30 mg may be used per burner after 31 December 2011
4(c)-III	P > 405 W	No limitation of use until 31 December 2011, 30 mg may be used per burner after 31 December 2011 No limitation of use until 31 December 2011; 40 mg may be used per burner after 31 December 2011
4(d)	Mercury in High Pressure Mercury (vapour) lamps (HPMV)	Expires on 13 April 2015
4(e)	Mercury in metal halide lamps (MH)	
4(f)	Mercury in other discharge lamps for special purposes not specifically mentioned in this Annex	
5(a)	Lead in glass of cathode ray tubes	
5(b)	Lead in glass of fluorescent tubes not exceeding 0,2 % by weight	
6(a)	Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35 % lead by v	veignt
6(b)	Lead as an alloying element in aluminium containing up to 0,4 % lead by weight	
6(c)	Copper alloy containing up to 4 % lead by weight	
7(a)	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)	
7(b)	Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signa	ling transmission and network management for telecommunications
7(c)-1	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors,	e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
7(c)-11	Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher	
7(c)-111	Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC	Expires on 1 January 2013 and after that date may be used in spare parts for EEE placed on the market
	Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC	Expires on 1 January 2013 and after that date may be used in spare parts for EEE placed on the market before 1 January 2013
7(c)-111		before 1 January 2013
	Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC Cadmium and its compounds in one shot pellet type thermal cut-offs	before 1 January 2013 Expires on 1 January 2012 and after that date may be used in spare parts for EEE placed on the market
7(c)-111 8(a)	Cadmium and its compounds in one shot pellet type thermal cut-offs	before 1 January 2013
7(c)-111 8(a) 8(b)	Cadmium and its compounds in one shot pellet type thermal cut-offs Cadmium and its compounds in electrical contacts	before 1 January 2013 Expires on 1 January 2012 and after that date may be used in spare parts for EEE placed on the market before 1 January 2012
7(c)-111 8(a)	Cadmium and its compounds in one shot pellet type thermal cut-offs	before 1 January 2013 Expires on 1 January 2012 and after that date may be used in spare parts for EEE placed on the market before 1 January 2012
7(c)-111 8(a) 8(b) 9	Cadmium and its compounds in one shot pellet type thermal cut-offs Cadmium and its compounds in electrical contacts Hexavalent chromium as an anticorrosion agent of the carbon steel cooling system in absorption refrigerators up to 0	before 1 January 2013 Expires on 1 January 2012 and after that date may be used in spare parts for EEE placed on the market before 1 January 2012 .75 % by weight in the cooling solution
7(c)-111 8(a) 8(b) 9 9(b)	Cadmium and its compounds in one shot pellet type thermal cut-offs Cadmium and its compounds in electrical contacts Hexavalent chromium as an anticorrosion agent of the carbon steel cooling system in absorption refrigerators up to 0 Lead in bearing shells and bushes for refrigerant-containing compressors for heating, ventilation, air conditioning and	before 1 January 2013 Expires on 1 January 2012 and after that date may be used in spare parts for EEE placed on the market before 1 January 2012 .75 % by weight in the cooling solution refrigeration (HVACR) applications
7(c)-111 8(a) 8(b) 9 9(b) 11(a)	Cadmium and its compounds in one shot pellet type thermal cut-offs Cadmium and its compounds in electrical contacts Hexavalent chromium as an anticorrosion agent of the carbon steel cooling system in absorption refrigerators up to 0 Lead in bearing shells and bushes for refrigerant-containing compressors for heating, ventilation, air conditioning and Lead used in C-press compliant pin connector systems	before 1 January 2013 Expires on 1 January 2012 and after that date may be used in spare parts for EEE placed on the market before 1 January 2012 .75 % by weight in the cooling solution refrigeration (HVACR) applications May be used in spare parts for EEE placed on the market before 24 September 2010
7(c)-111 8(a) 8(b) 9 9(b)	Cadmium and its compounds in one shot pellet type thermal cut-offs Cadmium and its compounds in electrical contacts Hexavalent chromium as an anticorrosion agent of the carbon steel cooling system in absorption refrigerators up to 0 Lead in bearing shells and bushes for refrigerant-containing compressors for heating, ventilation, air conditioning and	before 1 January 2013 Expires on 1 January 2012 and after that date may be used in spare parts for EEE placed on the market before 1 January 2012 .75 % by weight in the cooling solution refrigeration (HVACR) applications May be used in spare parts for EEE placed on the market before 24 September 2010 Expires on 1 January 2013 and after that date may be used in spare parts for EEE placed on the market
7(c)-111 8(a) 8(b) 9 9(b) 11(a) 11(b)	Cadmium and its compounds in one shot pellet type thermal cut-offs Cadmium and its compounds in electrical contacts Hexavalent chromium as an anticorrosion agent of the carbon steel cooling system in absorption refrigerators up to 0 Lead in bearing shells and bushes for refrigerant-containing compressors for heating, ventilation, air conditioning and Lead used in C-press compliant pin connector systems Lead used in other than C-press compliant pin connector systems	before 1 January 2013 Expires on 1 January 2012 and after that date may be used in spare parts for EEE placed on the market before 1 January 2012 .75 % by weight in the cooling solution refrigeration (HVACR) applications May be used in spare parts for EEE placed on the market before 24 September 2010 Expires on 1 January 2013 and after that date may be used in spare parts for EEE placed on the market before 1 January 2013
7(c)-111 8(a) 8(b) 9 9(b) 11(a) 11(b) 12	Cadmium and its compounds in one shot pellet type thermal cut-offs Cadmium and its compounds in electrical contacts Hexavalent chromium as an anticorrosion agent of the carbon steel cooling system in absorption refrigerators up to 0 Lead in bearing shells and bushes for refrigerant-containing compressors for heating, ventilation, air conditioning and Lead used in C-press compliant pin connector systems Lead used in other than C-press compliant pin connector systems Lead as a coating material for the thermal conduction module C-ring	before 1 January 2013 Expires on 1 January 2012 and after that date may be used in spare parts for EEE placed on the market before 1 January 2012 .75 % by weight in the cooling solution refrigeration (HVACR) applications May be used in spare parts for EEE placed on the market before 24 September 2010 Expires on 1 January 2013 and after that date may be used in spare parts for EEE placed on the market
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7(c)-111 8(a) 8(b) 9 9(b) 11(a) 11(b) 12 13(a) 13(b) 14 15 16 17 18(a) 19 20 21 23 24 25 26 27 29 30 31 32 33 34 36	Cadmium and its compounds in one shot pellet type thermal cut-offs Cadmium and its compounds in electrical contacts Hexavalent chromium as an anticorrosion agent of the carbon steel cooling system in absorption refrigerators up to 0 Lead in bearing shells and bushes for refrigerant-containing compressors for heating, ventilation, air conditioning and Lead used in C-press compliant pin connector systems Lead used in other than C-press compliant pin connector systems Lead used in other than C-press compliant pin connector systems Lead as a coating material for the thermal conduction module C-ring Lead in white glasses used for glasses used for reflectance standards Lead in solders consisting of more than two elements for the connection between the pins and the package of microprocessors with a lead content of more than 80 % and less than 85 % by weight Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated ci Lead in linear incandescent lamps with silicate coated tubes Lead halide as radiant agent in high intensity discharge (HID) lamps used for professional reprography applications Lead as activator in the fluorescent powder (1 % lead by weight or less) of discharge lamps when used as suntaning phosphors such as SMS ((Sr.Ba) 2 MgSi 2 O 7 /Pb) Lead as activator in the fluorescent powder (1 % lead by weight or less) of discharge lamps used for Liquid Crystal Displays (LCDs) Lead and cadmium in printing inks for the application of enamels on glasses, such as borosilicate and soda lime glasses Lead in solders of the soldering to machine discouter of the applications as main amalgam and with PbSn-Hg as auxiliary amalgam in very compact energy saving lamps (ESL) Lead oxide in glass used for bonding front and rear substrates of flat fluorescent lamps used for Liquid Crystal Displays (LCDs) Lead and cadmium in printing inks for the application of enamels on glasses, such as borosilicate and soda lime glasses Lead in solders for the soldering to machinet through	before 1 January 2013 Expires on 1 January 2012 and after that date may be used in spare parts for EEE placed on the market before 1 January 2012 .75 % by weight in the cooling solution refrigeration (HVACR) applications May be used in spare parts for EEE placed on the market before 24 September 2010 Expires on 1 January 2013 and after that date may be used in spare parts for EEE placed on the market before 1 January 2013 May be used in spare parts for EEE placed on the market before 24 September 2010 Expires on 1 January 2011 and after that date may be used in spare parts for EEE placed on the market before 1 January 2011 may be used in spare parts for EEE placed on the market before 24 September 2010 Expires on 1 January 2011 and after that date may be used in spare parts for EEE placed on the market before 1 January 2011 Expires on 1 September 2013 Expires on 1 September 2013 Expires on 1 January 2011 g lamps containing phosphors such as BSP (BaSi 2 O 5 :Pb) Expires on 1 June 2011 Expires on 1 June 2011 Expired on 24 September 2010 Expires on 24 September 2010 Expires on 24 September 2010
7(c)-111 8(a) 8(b) 9 9(b) 11(a) 11(b) 12 13(b) 14 15 16 17 18(a) 14 15 16 17 18(a) 20 21 20 21 20 21 20 21 23 24 25 26 27 29 30 31 32 33 34 36 37	Cadmium and its compounds in one shot pellet type thermal cut-offs Cadmium and its compounds in electrical contacts Hexavalent chromium as an anticorrosion agent of the carbon steel cooling system in absorption refrigerators up to 0 Lead in bearing shells and bushes for refrigerant-containing compressors for heating, ventilation, air conditioning and Lead used in other than C-press compliant pin connector systems Lead used in other than C-press compliant pin connector systems Lead used in other than C-press compliant pin connector systems Cadmium and lead in filter glasses used for optical applications Cadmium and lead in filter glasses and glasses used for reflectance standards Lead in solders consisting of more than two elements for the connection between the pins and the package of microprocessors with a lead content of more than 80 % and less than 85 % by weight Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated ci Lead in linear incandescent lamps with silicate coated tubes Lead halide as radiant agent in high intensity discharge (HID) lamps used for professional reprography applications Lead as activator in the fluorescent powder (1 % lead by weight or less) of discharge lamps when used as speciality lamps for diazoprinting reprography, lithography, insect traps, photochemical and curing processes containing phosphors such as SMS ((Sr, Ba) 2 MgSi 2 O 7; Pb) Lead as activator in the fluorescent powder (1 % lead by weight or less) of discharge lamps when used as sun tanning Lead with PbBiSn-Hg and PbInSn-Hg in specific compositions as main amalgam and with PbSn-Hg as auxiliary amalgam in very compact energy saving lamps (ESL) Lead an admium in printing inks for the application of enamels on glasses, such as borosilicate and soda lime glasses Lead in finishes of fine pitch components other than connectors with a pitch of 0.65 mm and less Lead in solders for the soldering to machine through hole discoidal and planar array ceramic multilayer capac	before 1 January 2013 Expires on 1 January 2012 and after that date may be used in spare parts for EEE placed on the market before 1 January 2012 .75 % by weight in the cooling solution irefrigeration (HVACR) applications May be used in spare parts for EEE placed on the market before 24 September 2010 Expires on 1 January 2013 and after that date may be used in spare parts for EEE placed on the market before 1 January 2013 May be used in spare parts for EEE placed on the market before 24 September 2010 Expires on 1 January 2011 and after that date may be used in spare parts for EEE placed on the market before 1 January 2011 and after that date may be used in spare parts for EEE placed on the market before 1 January 2011 Expires on 1 January 2011 Expires on 1 September 2013 Expires on 1 September 2013 Expires on 1 January 2011 g lamps containing phosphors such as BSP (BaSi 2 O 5 :Pb) Expires on 1 June 2011 Expires on 24 September 2010 and frit ring Expires on 24 September 2010 Expires used in high-powered loudspeakers with sound pressure levels of 100 dB (A) and more en or industrial lighting)
7(c)-111 8(a) 8(b) 9 9(b) 11(a) 11(b) 12 13(a) 13(b) 14 15 16 17 18(a) 19 20 21 23 24 25 26 27 29 30 31 32 33 34 36	Cadmium and its compounds in one shot pellet type thermal cut-offs Cadmium and its compounds in electrical contacts Hexavalent chromium as an anticorrosion agent of the carbon steel cooling system in absorption refrigerators up to 0 Lead in bearing shells and bushes for refrigerant-containing compressors for heating, ventilation, air conditioning and Lead used in C-press compliant pin connector systems Lead used in other than C-press compliant pin connector systems Lead used in other than C-press compliant pin connector systems Lead as a coating material for the thermal conduction module C-ring Lead in white glasses used for glasses used for reflectance standards Lead in solders consisting of more than two elements for the connection between the pins and the package of microprocessors with a lead content of more than 80 % and less than 85 % by weight Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated ci Lead in linear incandescent lamps with silicate coated tubes Lead halide as radiant agent in high intensity discharge (HID) lamps used for professional reprography applications Lead as activator in the fluorescent powder (1 % lead by weight or less) of discharge lamps when used as suntaning phosphors such as SMS ((Sr.Ba) 2 MgSi 2 O 7 /Pb) Lead as activator in the fluorescent powder (1 % lead by weight or less) of discharge lamps used for Liquid Crystal Displays (LCDs) Lead and cadmium in printing inks for the application of enamels on glasses, such as borosilicate and soda lime glasses Lead in solders of the soldering to machine discouter of the applications as main amalgam and with PbSn-Hg as auxiliary amalgam in very compact energy saving lamps (ESL) Lead oxide in glass used for bonding front and rear substrates of flat fluorescent lamps used for Liquid Crystal Displays (LCDs) Lead and cadmium in printing inks for the application of enamels on glasses, such as borosilicate and soda lime glasses Lead in solders for the soldering to machinet through	before 1 January 2013 Expires on 1 January 2012 and after that date may be used in spare parts for EEE placed on the market before 1 January 2012 .75 % by weight in the cooling solution refrigeration (HVACR) applications May be used in spare parts for EEE placed on the market before 24 September 2010 Expires on 1 January 2013 and after that date may be used in spare parts for EEE placed on the market before 1 January 2013 May be used in spare parts for EEE placed on the market before 24 September 2010 Expires on 1 January 2011 and after that date may be used in spare parts for EEE placed on the market before 1 January 2011 market before 1 January 2011 and after that date may be used in spare parts for EEE placed on the market before 1 January 2011 Expires on 1 January 2011 Expires on 1 September 2013 Expires on 1 January 2011 g lamps containing phosphors such as BSP (BaSi 2 O 5 :Pb) Expires on 1 June 2011 Expires on 24 September 2010 mand frit ring Expires on 24 September 2010 Expires used in high-powered loudspeakers with sound pressure levels of 100 dB (A) and more en or industrial lighting)
7(c)-111 8(a) 8(b) 9 9(b) 11(a) 11(b) 12 13(b) 14 15 16 17 18(a) 14 15 16 17 18(a) 20 21 20 21 20 21 20 21 23 24 25 26 27 29 30 31 32 33 34 36 37	Cadmium and its compounds in one shot pellet type thermal cut-offs Cadmium and its compounds in electrical contacts Hexavalent chromium as an anticorrosion agent of the carbon steel cooling system in absorption refrigerators up to 0 Lead in bearing shells and bushes for refrigerant-containing compressors for heating, ventilation, air conditioning and Lead used in other than C-press compliant pin connector systems Lead used in other than C-press compliant pin connector systems Lead used in other than C-press compliant pin connector systems Cadmium and lead in filter glasses used for optical applications Cadmium and lead in filter glasses and glasses used for reflectance standards Lead in solders consisting of more than two elements for the connection between the pins and the package of microprocessors with a lead content of more than 80 % and less than 85 % by weight Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated ci Lead in linear incandescent lamps with silicate coated tubes Lead halide as radiant agent in high intensity discharge (HID) lamps used for professional reprography applications Lead as activator in the fluorescent powder (1 % lead by weight or less) of discharge lamps when used as speciality lamps for diazoprinting reprography, lithography, insect traps, photochemical and curing processes containing phosphors such as SMS ((Sr, Ba) 2 MgSi 2 O 7; Pb) Lead as activator in the fluorescent powder (1 % lead by weight or less) of discharge lamps when used as sun tanning Lead with PbBiSn-Hg and PbInSn-Hg in specific compositions as main amalgam and with PbSn-Hg as auxiliary amalgam in very compact energy saving lamps (ESL) Lead an admium in printing inks for the application of enamels on glasses, such as borosilicate and soda lime glasses Lead in finishes of fine pitch components other than connectors with a pitch of 0.65 mm and less Lead in solders for the soldering to machine through hole discoidal and planar array ceramic multilayer capac	before 1 January 2013 Expires on 1 January 2012 and after that date may be used in spare parts for EEE placed on the market before 1 January 2012 .75 % by weight in the cooling solution irefrigeration (HVACR) applications May be used in spare parts for EEE placed on the market before 24 September 2010 Expires on 1 January 2013 and after that date may be used in spare parts for EEE placed on the market before 1 January 2013 May be used in spare parts for EEE placed on the market before 24 September 2010 Expires on 1 January 2011 and after that date may be used in spare parts for EEE placed on the market before 1 January 2011 and after that date may be used in spare parts for EEE placed on the market before 1 January 2011 Expires on 1 January 2011 Expires on 1 September 2013 Expires on 1 September 2013 Expires on 1 January 2011 g lamps containing phosphors such as BSP (BaSi 2 O 5 :Pb) Expires on 1 June 2011 Expires on 24 September 2010 Instruction 1 June 2010 Expires on 24 September 2010 Instruction 1 June 2010 Instruction 24 September 2010 Instruction 2



LAB NO. 报告号 : DATE 日期 PAGE 页码

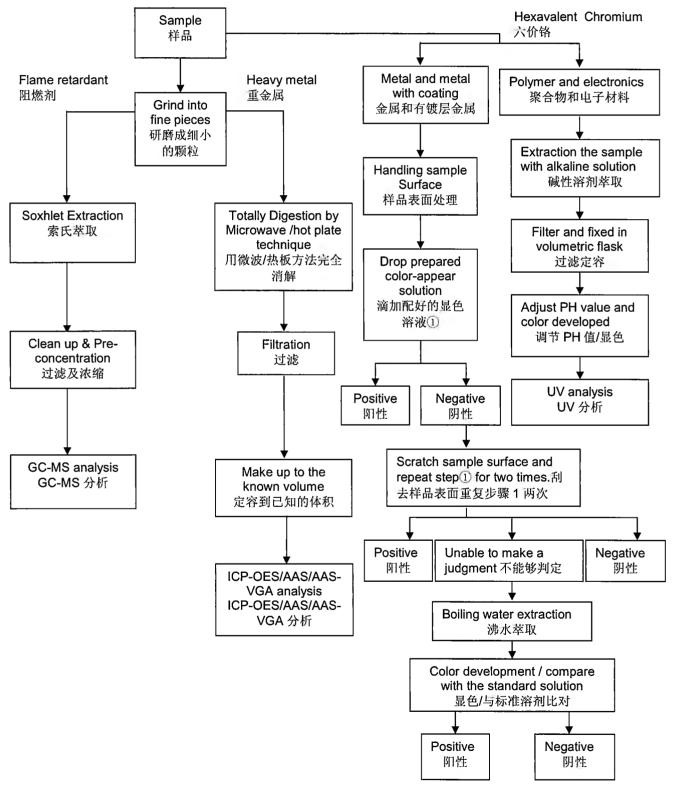
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(6611)202-0652 July 27, 2011 7 OF 7

APPENDIX

Test Procedures Flow Chart for the determination of RoHS (total heavy metals, Hexavalent Chromium and flame retardants)





Test ReportNumber : TWNC00226898Applicant:Littelfuse Philippines Inc.
LIMA Technology Center, Lipa City,
Malvar, BatangasDate : Oct 07, 2011Sample Description:
One (1) group of submitted samples said to be :
Part Description : PC 2407 (Bayer)
Date Sample Received : Oct 04, 2011
Date Test Started : Oct 05, 2011Date :
Test Started : Oct 05, 2011

Test Conducted : As requested by the applicant, for details please refer to attached pages.

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Test Conducted

(I) Test Result Summary :

Togt Itom	Result (ppm)
Test Item	Transparent Plastic
Heavy Metal	
Cadmium (Cd) content	ND
Lead (Pb) content	ND
Mercury (Hg) content	ND
Chromium VI (Cr ⁶⁺) content	ND
Polybrominated Biphenyls (PBBs)	
Monobrominated Biphenyls (MonoBB)	ND
Dibrominated Biphenyls (DiBB)	ND
Tribrominated Biphenyls (TriBB)	ND
Tetrabrominated Biphenyls (TetraBB)	ND
Pentabrominated Biphenyls (PentaBB)	ND
Hexabrominated Biphenyls (HexaBB)	ND
Heptabrominated Biphenyls (HeptaBB)	ND
Octabrominated Biphenyls (OctaBB)	ND
Nonabrominated Biphenyls (NonaBB)	ND
Decabrominated Biphenyl (DecaBB)	ND
Polybrominated Diphenyl Ethers (PBDEs)	
Monobrominated Diphenyl Ethers (MonoBDE)	ND
Dibrominated Diphenyl Ethers (DiBDE)	ND
Tribrominated Diphenyl Ethers (TriBDE)	ND
Tetrabrominated Diphenyl Ethers (TetraBDE)	ND
Pentabrominated Diphenyl Ethers (PentaBDE)	ND
Hexabrominated Diphenyl Ethers (HexaBDE)	ND
Heptabrominated Diphenyl Ethers (HeptaBDE)	ND
Octabrominated Diphenyl Ethers (OctaBDE)	ND
Nonabrominated Diphenyl Ethers (NonaBDE)	ND
Decabrominated Diphenyl Ether (DecaBDE)	ND
Halogen Content	
Fluorine (F)	ND
Chlorine (Cl)	ND
Bromine (Br)	ND
Iodine (I)	ND

Remarks: ppm = Parts per million based on weight of tested sample = mg/kg
ND = Not detected

Responsibility of Chemist : Irene Chiou / Kevin Liu / Cathy Chen

Date Sample Received : Oct 04, 2011 Test Period : Oct 05, 2011 To Oct 07, 2011



Test Conducted (II) ROHS Requi

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) RoHS Requirement:	
Restricted Substances	Limits
Cadmium (Cd) Content	0.01% (100ppm)
Lead (Pb) Content	0.1% (1000ppm)
Mercury (Hg) Content	0.1% (1000ppm)
Chromium VI (Cr ⁶⁺) Content	0.1% (1000ppm)
Polybrominated Biphenyls (PBBs)	0.1% (1000ppm)
Polybrominated Diphenyl Ehters (PBDEs)	0.1% (1000ppm)

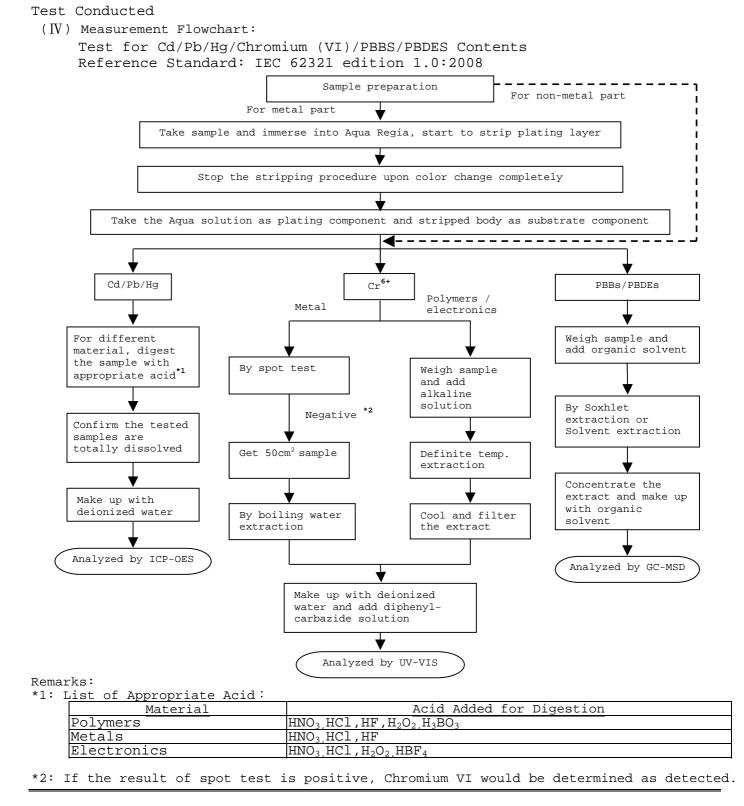
The above limits were quoted from 2002/95/EC and amendment 2005/618/EC for homogeneous material.

(Ⅲ) Test Method:

Test Item	Test Method	Reporting Limit
Cadmium (Cd) content	With reference to IEC 62321 edition 1.0:2008 in clause 8/9/10, by microwave digestion until the tested samples are totally dissolved and determined by ICP-OES.	2 ppm
Lead (Pb) content	With reference to IEC 62321 edition 1.0:2008 in clause 8/9/10, by microwave digestion until the tested samples are totally dissolved and determined by ICP-OES.	2 ppm
Mercury (Hg) content	With reference to IEC 62321 edition 1.0:2008 in clause 7, by microwave digestion until the tested samples are totally dissolved and determined by ICP-OES.	2 ppm
Chromium VI (Cr ⁶⁺) content	With reference to IEC 62321 edition 1.0:2008 in annex C, by alkaline digestion and determined by UV-Vis spectrophotometer.	1 ppm
Polybrominated Biphenyls (PBBs)	With reference to IEC 62321 edition 1.0:2008 in annex A, by solvent extraction and determined by GC-MSD and further HPLC confirmation when necessary.	5 ppm
Polybrominated Diphenyl Ethers (PBDEs)	With reference to IEC 62321 edition 1.0:2008 in annex A, by solvent extraction and determined by GC-MSD and further HPLC confirmation when necessary.	5 ppm
Halogen Content	With reference to EN 14582:2007 by calorimetric bomb with oxygen and determined by ion chromatography	50 ppm
Remark: Reporting limit = Quantitation limit of analyte in sample		

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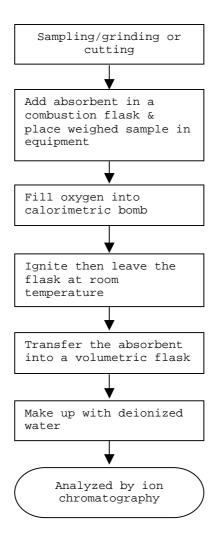






Test Conducted (IV) Measurement Flowchart:

Test for Halogen Content Reference Standard: EN 14582



End of Report

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Test Conducted

Photo



Material Name	Supplier
PC 2407	Bayer

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Test ReportNumber : TWNC00216857Applicant:Littelfuse Inc.
LIMA Technology Center, Lipa City,
Malvar, BatangasDate : Jul 25, 2011Sample Description:
One (1) group of submitted samples said to be :
Part Description: Aluminum Material

Date Sample Received: Jul 19, 2011Date Test Started: Jul 19, 2011

Test Conducted :

As requested by the applicant, for details please refer to attached pages.

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Test Conducted

(I) Test Result Summary :

Test Item	Result (ppm) Silvery Metal
Heavy Metal	
Cadmium (Cd) content	ND
Lead (Pb) content	ND
Mercury (Hg) content	ND
Chromium VI (Cr^{6+}) content (mg/kg with $50cm^2$)	Negative (< 0.02)

Responsibility of Chemist : Irene Chiou / Kevin Liu / Cathy Chen

Date Sample Received : Jul 19, 2011 Test Period : Jul 19, 2011 To Jul 25, 2011

(${\rm II}$) RoHS Requirement:

Restricted Substances	Limits
Cadmium (Cd) Content	0.01% (100ppm)
Lead (Pb) Content	0.1% (1000ppm)
Mercury (Hg) Content	0.1% (1000ppm)
Chromium VI (Cr ⁶⁺) Content	0.1% (1000ppm)

The above limits were quoted from 2002/95/EC and amendment 2005/618/EC for homogeneous material.



Test Conducted

(Ⅲ) Test Method:

Test Item	Test Method	Reporting Limit
Cadmium (Cd) content	With reference to IEC 62321 edition 1.0:2008 in clause 8/9/10, by microwave digestion until the tested samples are totally dissolved and determined by ICP-OES.	2 ppm
Lead (Pb) content	With reference to IEC 62321 edition 1.0:2008 in clause 8/9/10, by microwave digestion until the tested samples are totally dissolved and determined by ICP-OES.	2 ppm
Mercury (Hg) content With reference to IEC 62321 edition 1.0:2008 in clause 7, by microwave digestion until the tested samples are totally dissolved and determined by ICP-OES.		2 ppm
Chromium VI (Cr ⁶⁺) content	With reference to IEC 62321 edition 1.0:2008 in annex B, by boiling water extraction and determined by UV-Vis spectrophotometer.	0.02 mg/kg with 50 cm ²

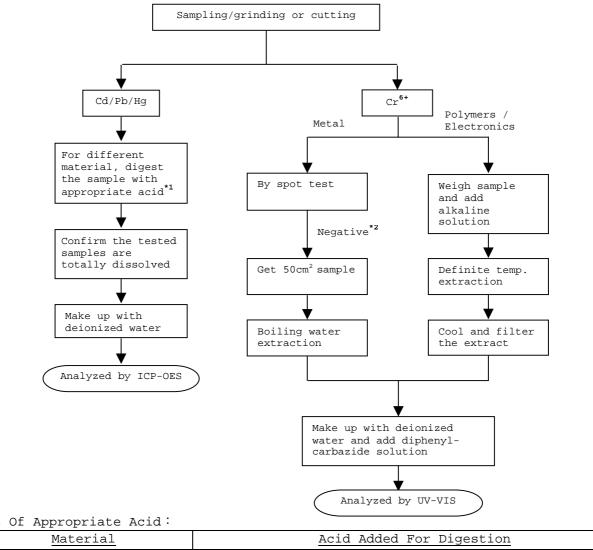
Remark: Reporting limit = Quantitation limit of analyte in sample



Test Conducted

(IV) Measurement Flowchart:

```
Test For Cd/Pb/Hg/Chromium (VI)
Reference Standard: IEC 62321 edition 1.0:2008
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Domoriza	•
Remarks	•

*1: List Of Appropriate Acid:

	Material	Acid Added For Digestion
	Polymers	HNO ₃ ,HCl,HF,H ₂ O ₂ ,H ₃ BO ₃
	Metals	HNO ₃ ,HCl,HF
	Electronics	HNO ₃ ,HCl,H ₂ O ₂ ,HBF ₄
*2: I	If the result of spot test i	s positive, Chromium VI would be determined as detected.

End of Report



Test Conducted



Photo

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Test ReportNumber : TWNC00216854Applicant:Littelfuse Inc.
LIMA Technology Center, Lipa City,
Malvar, Batangas.Date : Jul 27, 2011Sample Description:
One (1) group of submitted samples said to be :
Part Description : Steel
Date Sample Received : Jul 19, 2011
Date Test Started : Jul 19, 2011Number : TWNC00216854

Test Conducted :

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Test Conducted

(I) Test Result Summary :

Togt Itom	Result (ppm)	
Test Item	(1)	(2)
Heavy Metal		
Cadmium (Cd) content	ND	ND
Lead (Pb) content	ND	ND
Mercury (Hg) content	ND	ND
Chromium VI (Cr^{6+}) content (mg/kg with $50cm^2$)	Negative (< 0.02)	Negative (< 0.02)

Remarks: ppm = Parts per million based on weight of tested sample = mg/kg ND = Not detected < = Less than mg/kg with 50cm² = milligram per kilogram with 50 square centimetre Negative = A negative test result indicated positive observation was not found at the time of Test. = Due to the insufficient sample area, reduced total sample # surface of 10 cm^2 was used and the dilution factor was adjusted accordingly. Tested Components (1) Black Plating Layer (2) Silvery Metal Base Material Responsibility of Chemist : Irene Chiou / Kevin Liu / Cathy Chen Date Sample Received : Jul 19, 2011 Test Period : Jul 19, 2011 To Jul 27, 2011

(II) RoHS Requirement:

Restricted Substances	Limits
Cadmium (Cd) Content	0.01% (100ppm)
Lead (Pb) Content	0.1% (1000ppm)
Mercury (Hg) Content	0.1% (1000ppm)
Chromium VI (Cr ⁶⁺) Content	0.1% (1000ppm)

The above limits were quoted from 2002/95/EC and amendment 2005/618/EC for homogeneous material.



Test Conducted

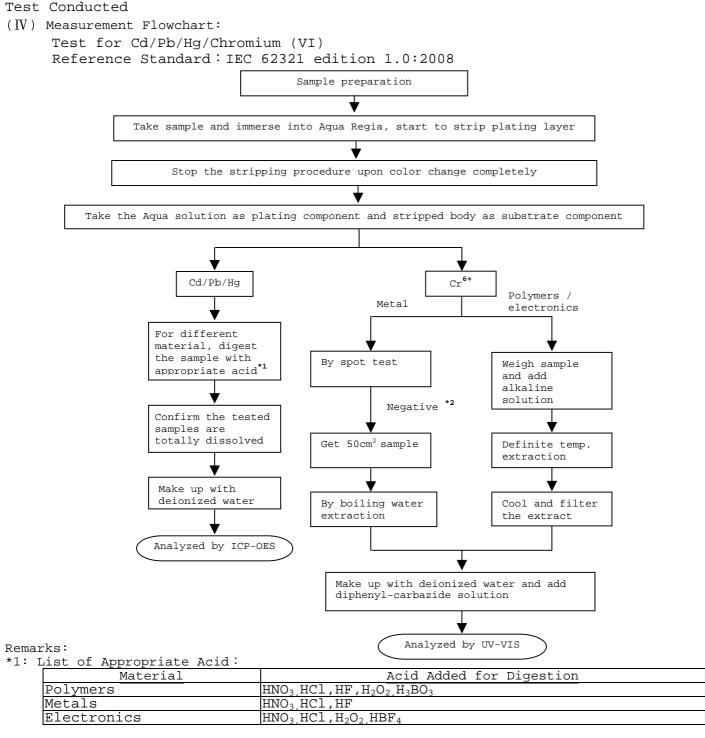
(Ⅲ) Test Method:

Test Item	Test Method	Reporting Limit
Cadmium (Cd) content	With reference to IEC 62321 edition 1.0:2008 in clause 8/9/10, by microwave digestion until the tested samples are totally dissolved and determined by ICP-OES.	2 ppm
Lead (Pb) content	With reference to IEC 62321 edition 1.0:2008 in clause 8/9/10, by microwave digestion until the tested samples are totally dissolved and determined by ICP-OES.	2 ppm
Mercury (Hg) content	With reference to IEC 62321 edition 1.0:2008 in clause 7, by microwave digestion until the tested samples are totally dissolved and determined by ICP-OES.	2 ppm
Chromium VI (Cr ⁶⁺) content	With reference to IEC 62321 edition 1.0:2008 in annex B, by boiling water extraction and determined by UV-Vis spectrophotometer.	0.02 mg/kg with 50cm ²

Remark: Reporting limit = Quantitation limit of analyte in sample

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*2: If the result of spot test is positive, Chromium VI would be determined as detected.

End of Report

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Test Conducted

Photo



Page 5 of 5



Test ReportNumber : TWNC00216856Applicant:Littelfuse Inc.
LIMA Technology Center, Lipa City,
Malvar, BatangasDate : Jul 25, 2011Sample Description:
One (1) group of submitted samples said to be :Sample :

Part Description: Copper AlloyDate Sample Received: Jul 19, 2011Date Test Started: Jul 20, 2011

Test Conducted :

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Test Conducted

(I) Test Result Summary :

Test Item	Result (ppm) Coppery Metal
Heavy Metal	
Cadmium (Cd) content	ND
Lead (Pb) content	46
Mercury (Hg) content ND	
Chromium VI (Cr ⁶⁺) content (mg/kg with 50cm ²)	Negative(< 0.02)(#)

(Ⅱ) RoHS Requirement:

Restricted Substances	Limits
Cadmium (Cd) Content	0.01% (100ppm)
Lead (Pb) Content	0.1% (1000ppm)
Mercury (Hg) Content	0.1% (1000ppm)
Chromium VI (Cr ⁶⁺) Content	0.1% (1000ppm)

The above limits were quoted from 2002/95/EC and amendment 2005/618/EC for homogeneous material.



Test Conducted

(Ⅲ) Test Method:

Test Item	Test Method	Reporting Limit
Cadmium (Cd) content With reference to IEC 62321 edition 1.0:2008 in clause 8/9/10, by microwave digestion until the tested samples are totally dissolved and determined by ICP-OES.		2 ppm
Lead (Pb) content	With reference to IEC 62321 edition 1.0:2008 in clause 8/9/10, by microwave digestion until the tested samples are totally dissolved and determined by ICP-OES.	2 ppm
Mercury (Hg) content	With reference to IEC 62321 edition 1.0:2008 in clause 7, by microwave digestion until the tested samples are totally dissolved and determined by ICP-OES.	2 ppm
Chromium VI (Cr ⁶⁺) content	With reference to IEC 62321 edition 1.0:2008 in annex B, by boiling water extraction and determined by UV-Vis spectrophotometer.	0.02 mg/kg with 50 cm ²

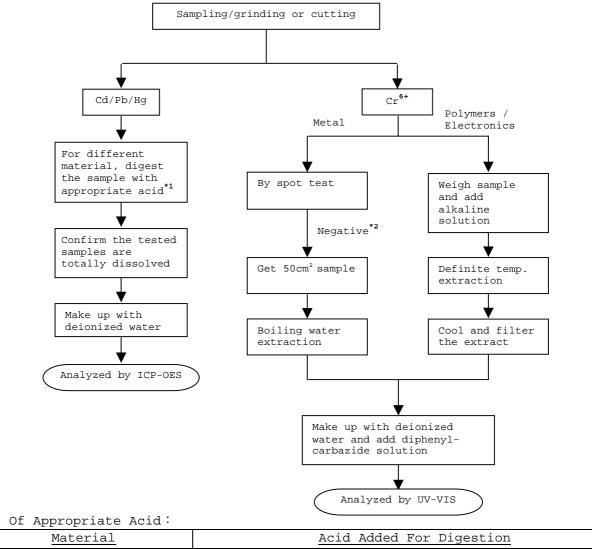
Remark: Reporting limit = Quantitation limit of analyte in sample



Test Conducted

(IV) Measurement Flowchart:

```
Test For Cd/Pb/Hg/Chromium (VI)
Reference Standard: IEC 62321 edition 1.0:2008
```



Remarks:	
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*1: List Of Appropriate Acid:

	Material	Acid Added For Digestion
	Polymers	HNO ₃ ,HCl,HF,H ₂ O ₂ ,H ₃ BO ₃
	Metals	HNO _{3,} HCl,HF
	Electronics	HNO ₃ ,HCl,H ₂ O ₂ ,HBF ₄
*2: 1	If the result of spot test i	s positive, Chromium VI would be determined as detected.

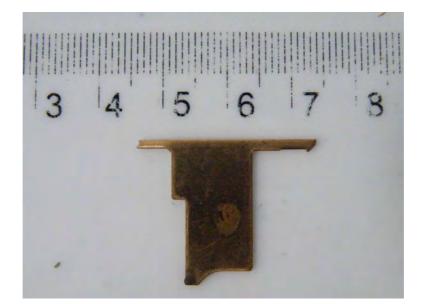
End of Report



Test Conducted

Photo





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Test Report Number : TWNC00238069 Applicant: Littelfuse, Philippines Inc. Date : Dec 27, 2011 LIMA Technology Center, Lipa City, Malvar, Batangas Sample Description: One (1) group of submitted samples said to be : Part Description : Metal Part Number : 65Mn Date Sample Received : Dec 22, 2011 Date Test Started : Dec 23, 2011

Test Conducted :

As requested by the applicant, for details please refer to attached pages.

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Test Conducted

(I) Test Result Summary :

To at them	Result (ppm)			
Test Item	(1)	(2)		
Heavy Metal				
Cadmium (Cd) content	ND	ND		
Lead (Pb) content	ND	ND		
Mercury (Hg) content	ND	ND		
Chromium VI (Cr^{6+}) content (mg/kg with $50cm^2$)	Negative (< 0.02)	Negative (< 0.02)		

Tested Components

(1) Silvery Metal Base Material

(2) Silvery Plating Layer

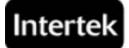
Responsibility of Chemist : Irene Chiou / Kevin Liu

Date Sample Received : Dec 22, 2011 Test Period : Dec 23, 2011 To Dec 26, 2011

(${\rm II}$) RoHS Requirement:

Restricted Substances	Limits
Cadmium (Cd) Content	0.01% (100ppm)
Lead (Pb) Content	0.1% (1000ppm)
Mercury (Hg) Content	0.1% (1000ppm)
Chromium VI (Cr ⁶⁺) Content	0.1% (1000ppm)

The above limits were quoted from 2002/95/EC and amendment 2005/618/EC for homogeneous material.

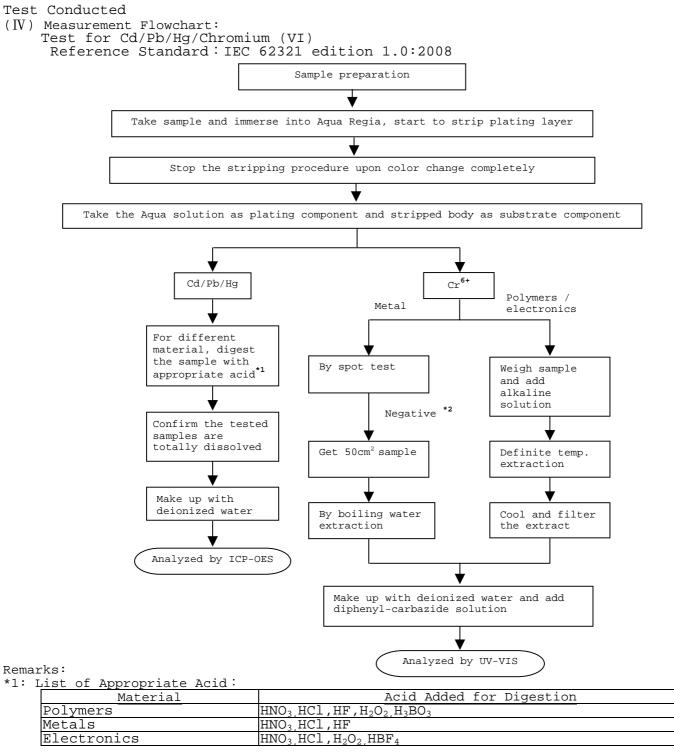


Test Conducted

Test Item	Test Method	Reporting Limit
Cadmium (Cd) content	With reference to IEC 62321 edition 1.0:2008 in clause 8/9/10, by microwave digestion until the tested samples are totally dissolved and determined by ICP-OES.	2 ppm
Lead (Pb) content	With reference to IEC 62321 edition 1.0:2008 in clause 8/9/10, by microwave digestion until the tested samples are totally dissolved and determined by ICP-OES.	2 ppm
Mercury (Hg) content	With reference to IEC 62321 edition 1.0:2008 in clause 7, by microwave digestion until the tested samples are totally dissolved and determined by ICP-OES.	2 ppm
Chromium VI (Cr ⁶⁺) content	With reference to IEC 62321 edition 1.0:2008 in annex B, by boiling water extraction and determined by UV-Vis Spectrophotometer.	0.02 mg/kg with 50 cm ²

Remark: Reporting limit = Quantitation limit of analyte in sample





*2: If the result of spot test is positive, Chromium VI would be determined as detected.

End of Report

Page 4 of 5



Test Conducted

Photo





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Page 5 of 5



Test ReportNumber : TWNC00238070Applicant:Littelfuse, Philippines Inc.
LIMA Technology Center, Lipa City,
Malvar, BatangasDate : Dec 27, 2011Sample Description:
One (1) group of submitted samples said to be :
Part Description : Neon Lamp sub-assay
Date Sample Received : Dec 22, 2011Date Test Started : Dec 22, 2011

Test Conducted :

As requested by the applicant, for details please refer to attached pages.

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Page 1 of 11

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Test Conducted

(I) Test Result Summary :

march Theory	Result	(ppm)
Test Item	(1)	(2)
Heavy Metal		
Cadmium (Cd) content	ND	ND
Lead (Pb) content	78	ND
Mercury (Hg) content	ND	ND
Chromium VI (Cr ⁶⁺) content (for non-metal material)	ND	ND
Chromium VI (Cr ⁶⁺) content (by boiling water		
extraction on metal)(mg/kg with $50 cm^2$)		
Polybrominated Biphenyls (PBBs)		
Monobrominated Biphenyls (MonoBB)	ND	ND
Dibrominated Biphenyls (DiBB)	ND	ND
Tribrominated Biphenyls (TriBB)	ND	ND
Tetrabrominated Biphenyls (TetraBB)	ND	ND
Pentabrominated Biphenyls (PentaBB)	ND	ND
Hexabrominated Biphenyls (HexaBB)	ND	ND
Heptabrominated Biphenyls (HeptaBB)	ND	ND
Octabrominated Biphenyls (OctaBB)	ND	ND
Nonabrominated Biphenyls (NonaBB)	ND	ND
Decabrominated Biphenyl (DecaBB)	ND	ND
Polybrominated Diphenyl Ethers (PBDEs)	-	
Monobrominated Diphenyl Ethers (MonoBDE)	ND	ND
Dibrominated Diphenyl Ethers (DiBDE)	ND	ND
Tribrominated Diphenyl Ethers (TriBDE)	ND	ND
Tetrabrominated Diphenyl Ethers (TetraBDE)	ND	ND
Pentabrominated Diphenyl Ethers (PentaBDE)	ND	ND
Hexabrominated Diphenyl Ethers (HexaBDE)	ND	ND
Heptabrominated Diphenyl Ethers (HeptaBDE)	ND	ND
Octabrominated Diphenyl Ethers (OctaBDE)	ND	ND
Nonabrominated Diphenyl Ethers (NonaBDE)	ND	ND
Decabrominated Diphenyl Ether (DecaBDE)	ND	ND
Halogen Content	-	1
Fluorine (F)	ND	ND
Chlorine (Cl)	ND	ND
Bromine (Br)	ND	ND
Iodine (I)	ND	ND
Phthalates		1
Di(2-ethylhexyl) Phthalate (DEHP)		
Dibutyl Phthalate (DBP)		
Benzyl Butyl Phthalate (BBP)		
Others		
Hexabromocyclododecane (HBCDD)		



Test Conducted

(I) Test Result Summary :

Teat Item	<u>Result</u>	: (ppm)
<u>Test Item</u>	(3)	(4)
Heavy Metal		
Cadmium (Cd) content	ND	ND
Lead (Pb) content	ND	ND
Mercury (Hg) content	ND	ND
Chromium VI (Cr ⁶⁺) content (for non-metal material)	ND	ND
Chromium VI (Cr ⁶⁺) content (by boiling water extraction on metal)(mg/kg with 50cm ²)		Negative (<0.02) (#)
Polybrominated Biphenyls (PBBs)	·	
Monobrominated Biphenyls (MonoBB)	ND	
Dibrominated Biphenyls (DiBB)	ND	
Tribrominated Biphenyls (TriBB)	ND	
Tetrabrominated Biphenyls (TetraBB)	ND	
Pentabrominated Biphenyls (PentaBB)	ND	
Hexabrominated Biphenyls (HexaBB)	ND	
Heptabrominated Biphenyls (HeptaBB)	ND	
Octabrominated Biphenyls (OctaBB)	ND	
Nonabrominated Biphenyls (NonaBB)	ND	
Decabrominated Biphenyl (DecaBB)	ND	
Polybrominated Diphenyl Ethers (PBDEs)	·	
Monobrominated Diphenyl Ethers (MonoBDE)	ND	
Dibrominated Diphenyl Ethers (DiBDE)	ND	
Tribrominated Diphenyl Ethers (TriBDE)	ND	
Tetrabrominated Diphenyl Ethers (TetraBDE)	ND	
Pentabrominated Diphenyl Ethers (PentaBDE)	ND	
Hexabrominated Diphenyl Ethers (HexaBDE)	ND	
Heptabrominated Diphenyl Ethers (HeptaBDE)	ND	
Octabrominated Diphenyl Ethers (OctaBDE)	ND	
Nonabrominated Diphenyl Ethers (NonaBDE)	ND	
Decabrominated Diphenyl Ether (DecaBDE)	ND	
Halogen Content		
Fluorine (F)	ND	
Chlorine (Cl)	272199	
Bromine (Br)	2257	
Iodine (I)	ND	



Test Conducted

(I) Test Result Summary :

Test Item		Result (ppm)		
		(3)	(4)	
Phthalates				
Di(2-ethylhexyl) Phthalate (DEHP)		ND		
Dibutyl Phthalate (DBP)		ND		
Benzyl Butyl Phthalate (BBP)		ND		
Others				
Hexabromocyclododecane (HBCDD)		ND		

Remarks: ppm = Parts per million based on weight of tested sample = mg/kg
ND = Not detected

< = Less than
mg/kg with 50cm² = milligram per kilogram with 50 square centimetre
Negative = A negative test result indicated positive observation
was not found at the time of Test.

= Due to the insufficient sample area, reduced total sample surface of 10 cm² was used and the dilution factor was adjusted accordingly.

Responsibility of Chemist : Irene Chiou / Kevin Liu / Cathy Chen

Date Sample Received : Dec 22, 2011 Test Period : Dec 22, 2011 To Dec 27, 2011

(II) RoHS Requirement:

Restricted Substances	Limits
Cadmium (Cd) Content	0.01% (100ppm)
Lead (Pb) Content	0.1% (1000ppm)
Mercury (Hg) Content	0.1% (1000ppm)
Chromium VI (Cr ⁶⁺) Content	0.1% (1000ppm)
Polybrominated Biphenyls (PBBs)	0.1% (1000ppm)
Polybrominated Diphenyl Ehters (PBDEs)	0.1% (1000ppm)

The above limits were quoted from 2002/95/EC and amendment 2005/618/EC for homogeneous material.



Test Conducted

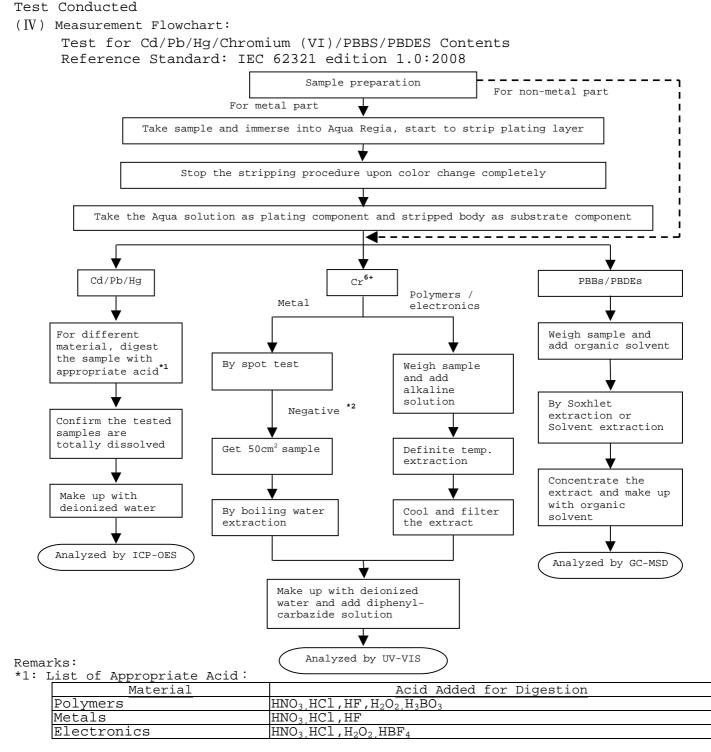
(Ⅲ) Test Method:

Test Method:		
Test Item	Test Method	Reporting Limit
Cadmium (Cd) content	With reference to IEC 62321 edition 1.0:2008 in clause 8/9/10, by microwave digestion until the tested samples are totally dissolved and determined by ICP-OES.	2 ppm
Lead (Pb) content	With reference to IEC 62321 edition 1.0:2008 in clause 8/9/10, by microwave digestion until the tested samples are totally dissolved and determined by ICP-OES.	2 ppm
Mercury (Hg) content	With reference to IEC 62321 edition 1.0:2008 in clause 7, by microwave digestion until the tested samples are totally dissolved and determined by ICP-OES.	2 ppm
Chromium VI (Cr ⁶⁺) content (for non- metal material) With reference to IEC 62321 edition 1.0:2008 in annex C, by alkaline digestion and determined by UV-Vis spectrophotometer.		l ppm
Chromium VI (Cr ⁶⁺) content (by boiling water extraction on metal)(mg/kg with 50cm ²)	With reference to IEC 62321 edition 1.0:2008 in annex B, by boiling water extraction and determined by UV-Vis Spectrophotometer.	0.02 mg/kg with 50cm
Polybrominated Biphenyls (PBBs)	With reference to IEC 62321 edition 1.0:2008 in annex A, by solvent extraction and determined by GC-MS and further HPLC-DAD confirmation when necessary.	5 ppm
Polybrominated Diphenyl Ethers (PBDEs)	With reference to IEC 62321 edition 1.0:2008 in annex A, by solvent extraction and determined by GC-MS and further HPLC-DAD confirmation when necessary.	5 ppm
Halogen Content	With reference to EN 14582:2007 by calorimetric bomb with oxygen and determined by Ion Chromatograph.	50 ppm
Phthalates	With reference to EN 14372: 2004, by solvent extraction and determined by GC-MSD	50 ppm
Hexabromocyclododecane (HBCDD)	With reference to USEPA 3540C, by solvent extraction and determined by GC-MSD	10 ppm

Remark: Reporting limit = Quantitation limit of analyte in sample

Page 5 of 11





*2: If the result of spot test is positive, Chromium VI would be determined as detected.

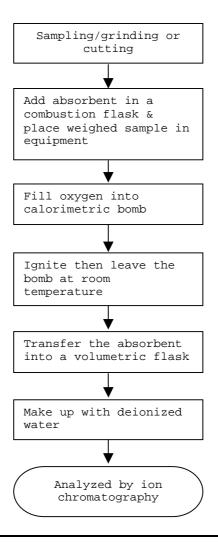
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Test Conducted (IV) Measurement Flowchart:

Test for Halogen Content Reference Standard: EN 14582



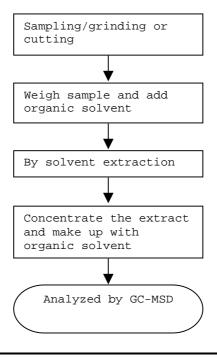
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Test Conducted

 (IV) Measurement Flowchart:

Test For Phthalates Contents Reference Method: EN 14372: 2004

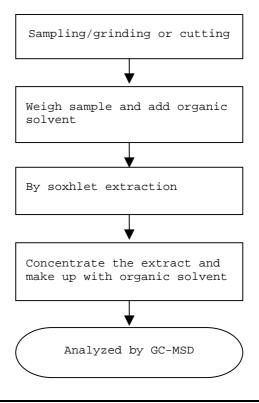




Test Conducted

 (IV) Measurement Flowchart:

Test For Hexabromocyclododecane (HBCDD) Reference Standard: USEPA 3540C





Tested Components:

- (1) Lamp (Mixed All Parts)
- (2) Blue Resistor With Golden/Yellow/Red/Green Printing (Mixed All Parts)
- (3) Black Cable Jacket With White Printing
- (4) Silvery Metal Wire

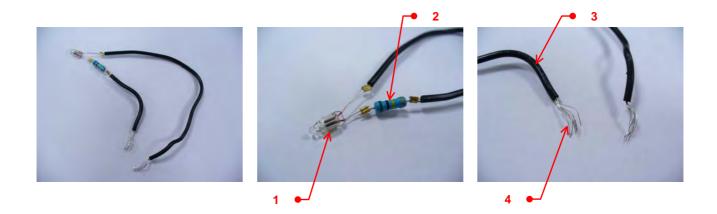
End of Report



Test Conducted

Number : TWNC00238070

Photo



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No. SHAEC1103841401 日期: 2011年03月31日 第1页,共4页

乐清市精饰电镀厂

浙江省乐清市北白象镇象塔南路42号

以下测试之样品是由申请者所提供及确认:镀锡层

SGS工作编号: 型号: 样品接收日期: 测试周期: 测试要求: 测试方法: 测试结果: 结论: 定快及咖以, 极物层 SP11-008489 - SH 配件 2011年03月28日 2011年03月28日 - 2011年03月31日 根据客户要求测试 请参见下一页 请参见下一页

基于所送样品进行的测试,测试结果与欧盟RoHS指令2002/95/EC以及后续修正指 令的要求相符

還标标准技术服务有限公司 授权签名

Fan Jingjie, JJ范晶捷

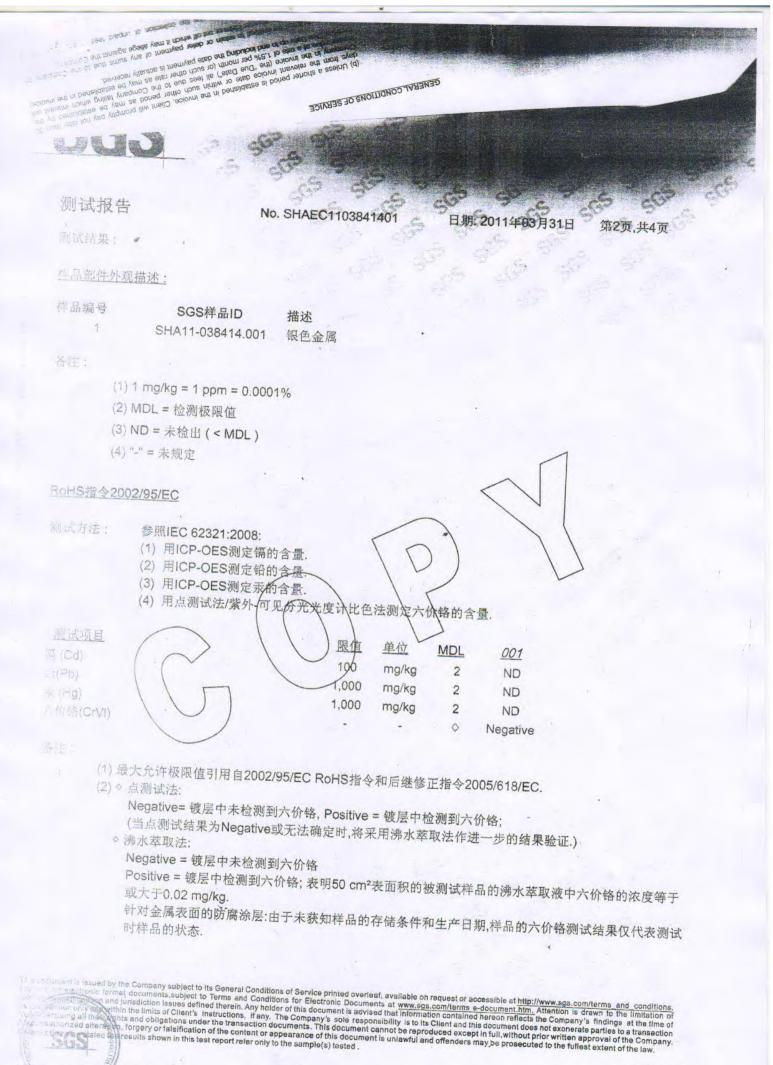
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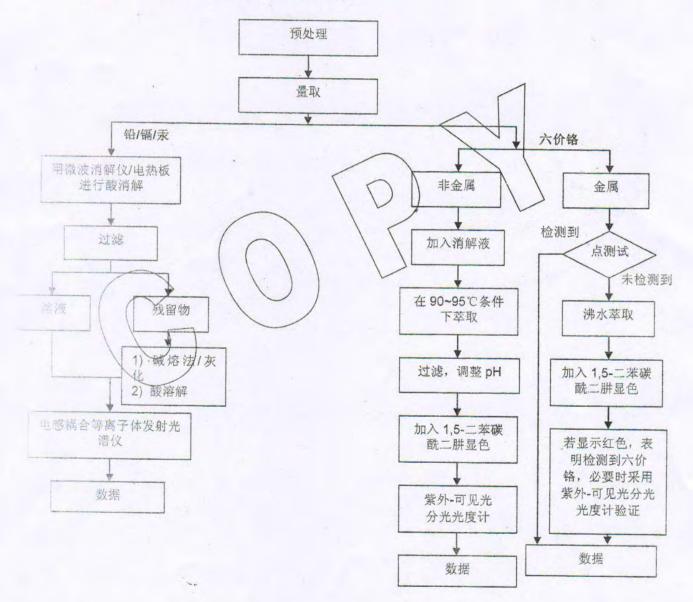
附件

RoHS 测试流程图

1) 分析人员: 肖飞/徐双/赵旭东

2) 项目负责人: 张春华/徐亮

3) 样品按照下述流程被完全消解(六价铬测试除外)



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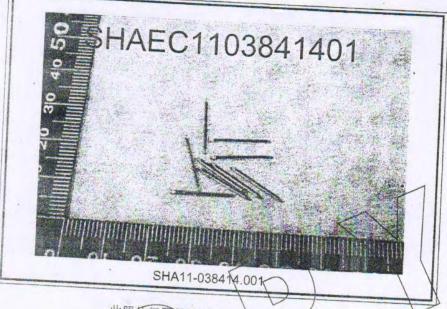
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No. SHAEC1102902201

日期: 2011年03月18日

第1页,共4页

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浙江省乐清市北门象镇象塔南路42号

以下测试之样品是由申请者所提供及确认:镀锌层 SGS工作编号: 划号: 配件 样品接收日期: 测试周期: 测试要求: 测试方法: 测试结果: 结论:

SP11-006643 - SH 2011年03月14日 2011年03月14日 - 2011年03月18日 根据客户要求测试 请参见下一页 请参见下一页 基于所送样品进行的测试,测试结果与欧盟RoHS指令2002/95/EC以及后续修工信 令的要求相符

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Fan Jingjie, JJ范晶捷

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No. SHAEC1102902201 日期: 201

日期: 2011年03月18日

第2页,共4页

测试结果:

样品部件外观描述:

样品编号	SGS样品ID	描述		
1	SHA11-029022.001	银蓝色金属		

备注:

- (1) 1 mg/kg = 1 ppm = 0.0001%
- (2) MDL = 检测极限值
- (3) ND = 未检出 (< MDL)
- (4) "-" = 未规定

RoHS指令2002/95/EC

测试方法:

- 参照IEC 62321:2008:
 - (1) 用ICP-OES测定镉的含量.
- (2) 用ICP-OES测定铅的含量
- (3) 用ICP-OES测定汞的含量.
- (4) 用点测试法/紫外-可见分光光度计比色法测定大价铬的含量.

测试项目	(夏道	单位	MDL	001
镉 (Cd)	11	100	mg/kg	2	ND
铅(Pb)	$\langle \cup \rangle$	1,000	mg/kg	2	ND
汞 (Hg)		1,000	mg/kg	2	ND
六价铬(CrVI)			-	0	Negative

备注:

- (1) 最大允许极限值引用自2002/95/EC RoHS指令和后继修正指令2005/618/EC.
- (2) ◇ 点测试法:

Negative= 镀层中未检测到六价铬, Positive = 镀层中检测到六价铬;

(当点测试结果为Negative或无法确定时,将采用沸水萃取法作进一步的结果验证.)

- ◇ 沸水萃取法:
 - Negative = 镀层中未检测到六价铬

Positive = 镀层中检测到六价铬; 表明50 cm²表面积的被测试样品的沸水萃取液中六价铬的浓度等于或大于0.02 mg/kg.

针对金属表面的防腐涂层:由于未获知样品的存储条件和生产日期,样品的六价铬测试结果仅代表测试时样品的状态.

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No. SHAEC1102902201

日期: 2011年03月18日

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附件

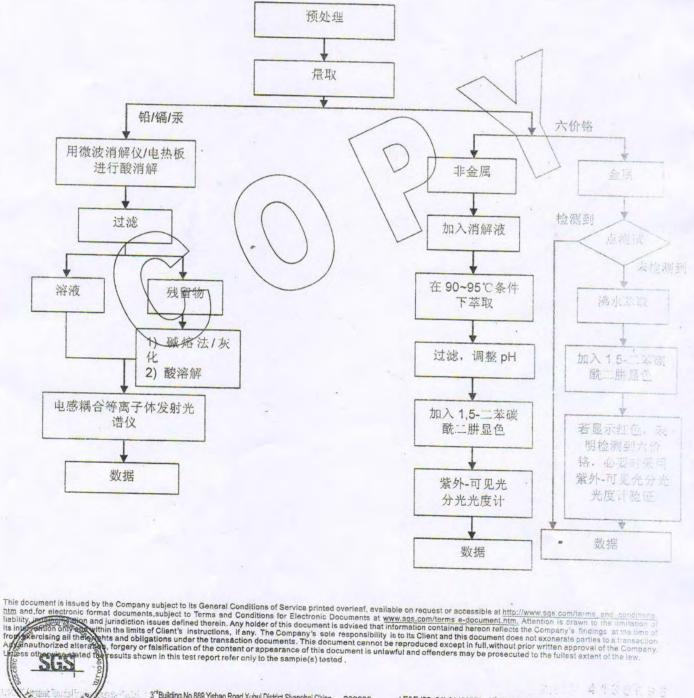
RoHS 测试流程图

1) 分析人员: 肖飞/徐双/赵旭东

A

2) 项目负责人: 张春华/徐亮

3) 样品按照下述流程被完全消解(六价铬测试除外)



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JIAGANG SYNTHETIC MATERIALS CO LTD OF JIAXING SHITONG ROAD, XIUZHOU INDUSTRY GARDEN OF JIAXING

The following sample(s) was/were submitted and identified on behalf of the clients as : EPOXY POTTING MATERIAL

SGS Job No. :	SP11-006182 - SH
Buyer :	PANASONIC
Composition :	EPOXY AND HARDENER
Supplier :	JIAGANG SYNTHETIC MATERIALS CO LTD OF JIAXING
Model No. :	910(black)
Date of Sample Received :	10 Mar 2011
Testing Period :	10 Mar 2011 - 16 Mar 2011
Test Requested :	Selected test(s) as requested by client.
Test Method :	Please refer to next page(s).
Test Results :	Please refer to next page(s).
Conclusion :	Based on the performed tests on submitted samples, the results comply with the RoHS Directive 2002/95/EC and its subsequent amendments.

Signed for and on behalf of SGS-CSTC Ltd.

Fan Jingjie, JJ Approved Signatory

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Test Results :

Test Part Description :

Specimen No.	SGS Sample ID	Description
1	SHA11-026924.001	Black solid

Remarks :

- (1) 1 mg/kg = 1 ppm = 0.0001%
- (2) MDL = Method Detection Limit
- (3) ND = Not Detected (< MDL)
- (4) "-" = Not Regulated

RoHS Directive 2002/95/EC

Test Method : With reference to IEC 62321:2008

- (1) Determination of Cadmium by ICP-OES.
- (2) Determination of Lead by ICP-OES.
- (3) Determination of Mercury by ICP-OES.
- (4) Determination of Hexavalent Chromium by Colorimetric Method using UV-Vis.

(5) Determination of PBBs / PBDEs content by GC-MS.

Test Item(s)	Limit	Unit	MDL	001	
Cadmium (Cd)	100	mg/kg	2	ND	
Lead (Pb)	1,000	mg/kg	2	ND	
Mercury (Hg)	1,000	mg/kg	2	ND	
Hexavalent Chromium (CrVI)	1,000	mg/kg	2	ND	
Sum of PBBs	1,000	mg/kg	-	ND	
Monobromobiphenyl	1 (H)	mg/kg	5	ND	
Dibromobiphenyl		mg/kg	5	ND	
Tribromobiphenyl	-	mg/kg	5	ND	
Tetrabromobiphenyl	-	mg/kg	5	ND	
Pentabromobiphenyl	-	mg/kg	5	ND	
Hexabromobiphenyl	-	mg/kg	5	ND	
Heptabromobiphenyl		mg/kg	5	ND	
Octabromobiphenyl	=	mg/kg	5	ND	
Nonabromobiphenyl	-	mg/kg	5	ND	
Decabromobiphenyl	-	mg/kg	5	ND	
Sum of PBDEs	1,000	mg/kg	40	ND	
Monobromodiphenyl ether		mg/kg	5	ND	

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Test Report	No. SHAEC11026924	01	Date: 16	Mar 2011	Page 3 of 8
Test Item(s)	Limit	Unit	MDL	<u>001</u>	
Dibromodiphenyl ether		mg/kg	5	ND	
Tribromodiphenyl ether	-	mg/kg	5	ND	
Tetrabromodiphenyl ether	÷	mg/kg	5	ND	
Pentabromodiphenyl ether	14	mg/kg	5	ND	
Hexabromodiphenyl ether		mg/kg	5	ND	
Heptabromodiphenyl ether		mg/kg	5	ND	
Octabromodiphenyl ether	-	mg/kg	5	ND	
Nonabromodiphenyl ether	-	mg/kg	5	ND	
Decabromodiphenyl ether		mg/kg	5	ND	

Notes :

(1) The maximum permissible limit is quoted from the document 2005/618/EC amending RoHS directive 2002/95/EC

Polynuclear Aromatic Hydrocarbons (PAH)

Test Method : With reference to ZEK 01.2-08 of German ZLS and its amendments, analysis was performed by GC-MS.

Test Item(s)	Unit	MDL	001	
Sum of 16 PAH	mg/kg	-	ND	
Naphthalene(NAP)	mg/kg	0.2	ND	
Acenaphthylene(ANY)	mg/kg	0.2	ND	
Acenaphthene(ANA)	mg/kg	0.2	ND	
Fluorene(FLU)	mg/kg	0.2	ND	
Phenanthrene(PHE)	mg/kg	0.2	ND	
Anthracene(ANT)	mg/kg	0.2	ND	
Fluoranthene(FLT)	mg/kg	0.2	ND	
Pyrene(PYR)	mg/kg	0.2	ND	
Benzo(a)anthracene(BaA)	mg/kg	0.2	ND	
Chrysene(CHR)	mg/kg	0.2	ND	
Benzo(b)fluoranthene(BbF)	mg/kg	0.2	ND	
Benzo(k)fluoranthene(BkF)	mg/kg	0.2	ND	
Benzo(a)pyrene(BaP)	mg/kg	0.2	ND	
Indeno(1,2,3-c,d)pyrene(IPY)	mg/kg	0.2	ND	
Dibenzo(a,h)anthracene(DBA)	mg/kg	0.2	ND	
Benzo(g,h,i)perylene(BPE)	mg/kg	0.2	ND	

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ZEK 01.2-08: Restraining maximum values for products

Parameter	Category 1	Category 2	Category 3	
	Material indented to be put in the mouth or material for toys with normal skin contact for children aged < 36 months	Materials which are not included in Category 1, with predictable contact with the skin longer than 30 s. (long-term skin contact)	Materials which are not included in Category 1 or 2, with predictable skin contact up to 30 s (short-term skin contact).	
Benzo[a]pyrene (mg/kg)	<mdl (<0.2)***<="" td=""><td>1</td><td>20</td></mdl>	1	20	
Sum of 16 PAH(US EPA) (mg/kg)**	<mdl (<0.2)***<="" td=""><td>10</td><td>200</td></mdl>	10	200	

Remark : ** = Only PAH substances >0.2 mg/kg are taken into account while calculating the sum of PAH *** = In case that the maximum values exceed the limits of category 1, but are within the limits of category 2, one may confirm the suitability of the tested material which is indented to be put in the mouth by additional specific migration tests of PAH components based on DIN EN 1186ff and §64 LFGB 80.30-1. The conclusion of the migration test results must be made based on food law criteria.

PFOS (Perfluorooctane Sulfonates)

Test Method : With reference to US EPA 3550C: 2007, analysis was performed by HPLC-MS.

Test Item(s)	Unit	MDL	001
Perfluorooctane Sulfonates (PFOS) and related	mg/kg	10	ND
Acid,Metal Salt and Amide			

Notes :

- (1) PFOS Reference Information: Entry 53 of Regulation (EC) No 552/2009 amending Annex XVII of REACH Regulation (EC) No 1907/2006 (previously restricted under Directive 2006/122/EC)
 (i) May not be placed on the market or used as a substance or constituent of preparations in a concentration equal to or higher than 0.005 % by mass.
 - (ii) May not be placed on the market in semi-finished products or articles, or parts thereof, if the concentration of PFOS is equal to or higher than 0.1 % by mass calculated with reference to the mass of structurally or microstructurally distinct parts that contain PFOS or, for textiles or other coated materials, if the amount of PFOS is equal to or higher than 1µg /m² of the coated material. Please refer to Regulation (EC) No 552/2009 to get more detail information

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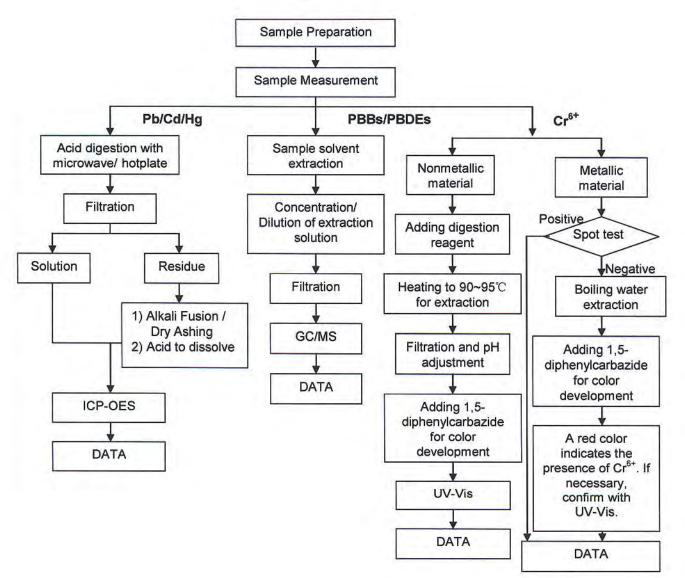
ATTACHMENTS

RoHS Testing Flow Chart

1) Name of the person who made testing: Allen Xiao/ Even Xu / Andy Zhao /Elim Lin

2) Name of the person in charge of testing: Jeff Zhang/George Xu/Tracy Yue

 These samples were dissolved totally by pre-conditioning method according to below flow chart. (Cr⁶⁺ and PBBs/PBDEs test method excluded)



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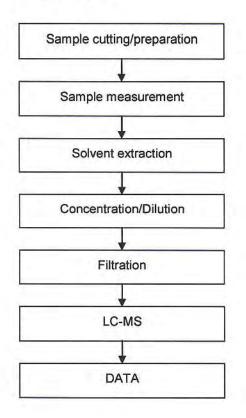
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PFOS Testing Flow Chart

1) Name of the person who made testing: Judy Li

2) Name of the person in charge of testing: Nancy Du



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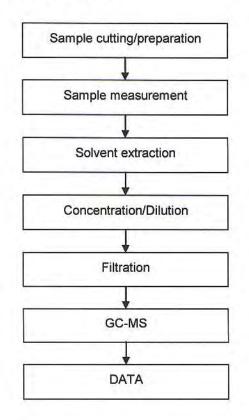
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PAHs Testing Flow Chart

1) Name of the person who made testing: Jessy Huang

2) Name of the person in charge of testing: Tracy Yue



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Sample photo:



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